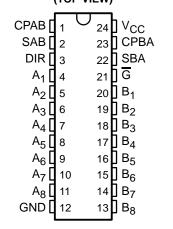
- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Independent Register for A and B Buses
- CY54FCT646T
 - 48-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT646T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

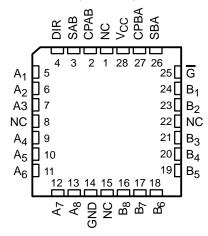
description

The 'FCT646T devices consist of a bus transceiver circuit with 3-state, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers as the appropriate

CY54FCT646T...D PACKAGE CY74FCT646T...Q OR SO PACKAGE (TOP VIEW)



CY54FCT646T ... L PACKAGE (TOP VIEW)



NC - No internal connection

clock pin goes to a high logic level. Output-enable (\overline{G}) and direction (DIR) inputs control the transceiver function. In the transceiver mode, data present at the high-impedance port can be stored in either the A or B register, or in both. Select controls (SAB, SBA) can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{G} is low. In the isolation mode (\overline{G}) is high), A data can be stored in the B register and/or B data can be stored in the A register.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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CY54FCT646T, CY74FCT646T 8-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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PIN DESCRIPTION

NAME	DESCRIPTION
Α	Data register A inputs, data register B outputs
В	Data register B inputs, data register A outputs
CPAB, CPBA	Clock-pulse inputs
SAB, SBA	Output data-source-select inputs
DIR, G	Output-enable inputs

ORDERING INFORMATION

TA	PACI	KAGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP - Q	Tape and reel	5.4	CY74FCT646CTQCT	FCT646C
	SOIC - SO	Tube	5.4	CY74FCT646CTSOC	FCT646C
	3010 - 30	Tape and reel	5.4	CY74FCT646CTSOCT	FC1646C
	QSOP - Q	Tape and reel	6.3	CY74FCT646ATQCT	FCT646A
–40°C to 85°C	SOIC - SO	Tube	6.3	CY74FCT646ATSOC	FCT646A
	3010 - 30	Tape and reel	6.3	CY74FCT646ATSOCT	FC1046A
	QSOP - Q	Tape and reel	9	CY74FCT646TQCT	FCT646
	SOIC - SO	Tube	9	CY74FCT646TSOC	FCT646
	3010 - 30	Tape and reel	9	CY74FCT646TSOCT	FC1046
	LCC – L	Tube	6	CY54FCT646CTLMB	
–55°C to 125°C	CDIP – D	Tube	7.7	CY54FCT646ATDMB	
-55 0 10 125 0	LCC – L	Tube	7.7	CY54FCT646ATLMB	
	LCC - L	Tube	11	CY54FCT646TLMB	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

		INP	UTS			DATA	\ I/O‡	OPERATION
G	DIR	CPAB	СРВА	SAB	SBA	A ₁ -A ₈	B ₁ -B ₈	OR FUNCTION
Н	Х	H or L	H or L	Х	Х	Input	Input	Isolation
Н	Χ	1	1	Χ	X	Input	Input	Store A and B data
L	L	Χ	Х	Χ	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

H = High logic level, L = Low logic level, ↑ = Low-to-high transition, X = Don't care



[‡] The data output functions can be enabled or disabled by various signals at the \overline{G} or DIR inputs. Data input functions always are enabled, i.e., data at the bus pins is stored on every low-to-high transition of the clock inputs.

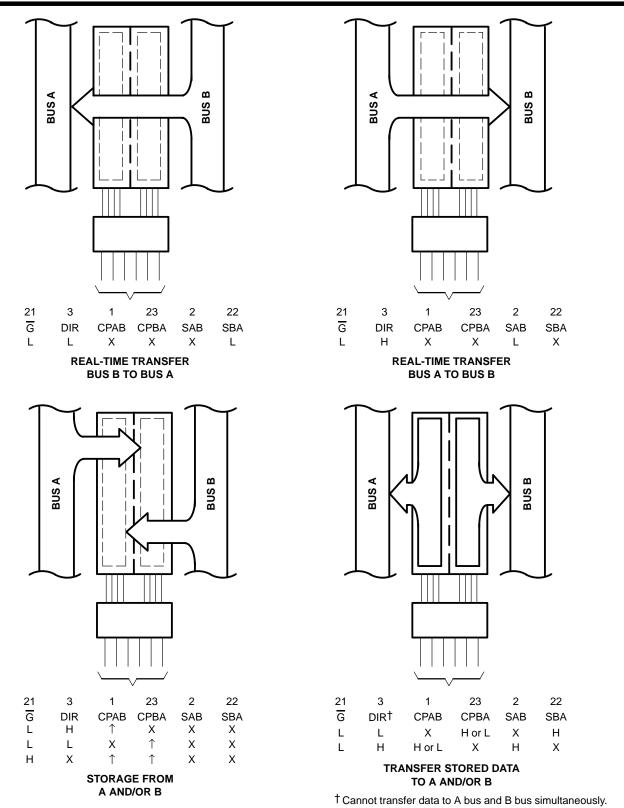
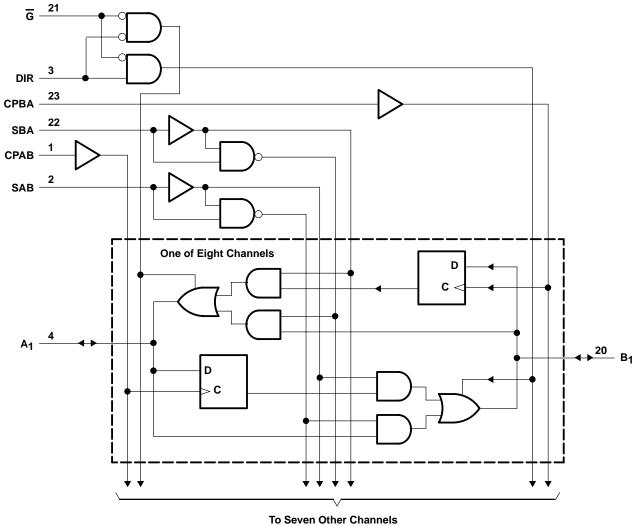


Figure 1. Bus-Management Functions



logic diagram (positive logic)



Pin numbers shown are for the Q and SO packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range to ground potential	\dots –0.5 V to 7 V
DC input voltage range	\dots –0.5 V to 7 V
DC output voltage range	\dots –0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	61°C/W
SO package	46°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stq}	-65° C to 150° C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 2)

		CY54FCT646T			CY7	74FCT64	6T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
loh	High-level output current			-12			-32	mA
l _{OL}	Low-level output current			48			64	mA
T _A	Operating free-air temperature	-55		125	-40	•	85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		OT CONDITION		CY	54FCT64	ŀ6T	CY	74FCT64	l6T			
PARAMETER		ST CONDITIONS	5	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT		
Vive	V _{CC} = 4.5 V,	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V		
VIK	V _{CC} = 4.75 V,	$I_{IN} = -18 \text{ mA}$						-0.7	-1.2	V		
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3							
Voн	V _{CC} = 4.75 V	$I_{OH} = -32 \text{ mA}$					2			V		
	VCC = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3				
Vai	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 48 mA			0.3	0.55				V		
VOL	V _{CC} = 4.75 V,	I _{OL} = 64 mA						0.3	0.55	V		
V _{hys}	All inputs				0.2			0.2		V		
	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = V_{CC}$				5						
lį	V _{CC} = 5.25 V,	$V_{IN} = V_{CC}$							5	μΑ		
1	$V_{CC} = 5.5 \text{ V},$	$V_{1N} = 2.7 \text{ V}$				±1				μА		
liH	$V_{CC} = 5.25 \text{ V},$	$V_{1N} = 2.7 \text{ V}$							±1	μΑ		
1	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = 0.5 V$				±1				μА		
ΙΙL	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = 0.5 V$							±1	μΑ		
lozu	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 2.7 V				10			μΑ			
IOZH	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V							10	μΑ		
lozu	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0.5 V				-10				μΑ		
lozl	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V							-10	μΛ		
los‡	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0 V		-60	-120	-225				mA		
1087	$V_{CC} = 5.25 \text{ V},$	$V_{OUT} = 0 V$					-60	-120	-225	ША		
l _{off}	$V_{CC} = 0 V$,	V _{OUT} = 4.5 V				±1			±1	μΑ		
loo	$V_{CC} = 5.5 \text{ V},$	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA		
Icc	$V_{CC} = 5.25 \text{ V},$	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2	ША		
	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}$	↓ V\$, f ₁ = 0, Outp	uts open		0.5	2						
ΔICC	V _{CC} = 5.25 V, V _{IN} = 3	.4 V§, f ₁ = 0, Out	puts open					0.5	2	mA		
loos¶	V_{CC} = 5.5 V, One input switching at 50% duty cycle, Outputs open, \overline{G} = DIR = GND, SAB = \overline{SBA} = GND, $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V				0.06	0.12				mA/		
ICCD¶	$V_{CC} = 5.25 \text{ V}, \text{ One inp}$ Outputs open, $\overline{G} = \text{DIR}$ $V_{IN} \le 0.2 \text{ V or } V_{IN} \ge V_{IN}$	R = GND, SAB = S						0.06	0.12	MHz		

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

[¶] This parameter is derived for use in total power-supply calculations.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		CT CONDITION	0	CY	54FCT64	16T	CY	74FCT64	ŀ6Т	LINIT
PARAMETER	11	EST CONDITION	5	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
		One bit switching at f ₁ = 5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
f ₀ = 10 Outputs G = DIF	$V_{CC} = 5.5 \text{ V},$ $f_0 = 10 \text{ MHz},$	at 50% duty cycle	V _{IN} = 3.4 V or GND		1.2	3.4				mA
	Outputs open, $\overline{G} = DIR = GND$, $SAB = \overline{SBA} = GND$	= GND, Eight bits	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		2.8	5.6				IIIA
IC#			V _{IN} = 3.4 V or GND		5.1	14.6				
10"		One bit switching at f ₁ = 5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	
	$V_{CC} = 5.25 \text{ V},$ $f_0 = 10 \text{ MHz},$	at 50% duty cycle	V _{IN} = 3.4 V or GND					1.2	3.4	mA
	Outputs open, $\overline{G} = DIR = GND,$ $SAB = \overline{SBA} = GND$	Eight bits switching at f ₁ = 5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					2.8	5.6	ША
		at 50% duty cycle	V _{IN} = 3.4 V or GND					5.1	14.6	
C _i					6	10		6	10	pF
Co					8	12		8	12	pF

 $^{^{\#}}$ IC = ICC + Δ ICC × D_H × N_T + ICCD(f₀/2 + f₁ × N₁)

Where:

IC = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

 N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

 \parallel Values for these conditions are examples of the ICC formula.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		CY54FCT646T		CY54FC1	54FCT646AT CY54FCT646CT			UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t_W	Pulse duration	6		5		5		ns
t _{su}	Setup time, data before CPAB↑ or CPBA↑	4.5		2		2		ns
t _h	Hold time, data after CPAB↑ or CPBA↑	2		1.5		1.5		ns

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		CY74FCT646T		CY74FCT646AT CY74FCT646CT			UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration	6		5		5		ns
t _{su}	Setup time, data before CPAB↑ or CPBA↑	4		2		2		ns
t _h	Hold time, data after CPAB↑ or CPBA↑	2		1.5	Ī	1.5		ns

switching characteristics over operating free-air temperature range (see Figure 2)

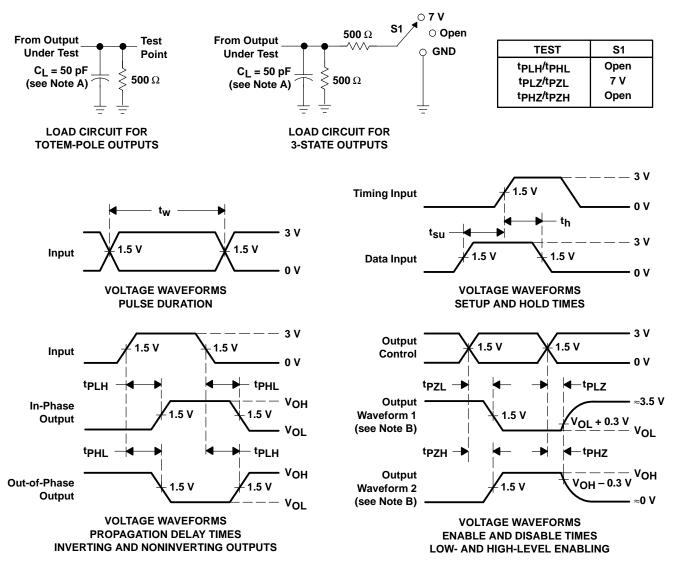
PARAMETER	FROM	то	CY54FC	T646T	CY54FCT646AT		CY54FCT646CT		UNIT
PARAMETER	(INPUT)	(INPUT) (OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNII
^t PLH	A or B	B or A	2	11	2	7.7	1.5	6	ns
t _{PHL}		BUIA	2	11	2	7.7	1.5	6	115
^t PZH	DIR	A or B	2	15	2	10.5	1.5	8.9	ns
t _{PZL}		AUID	2	15	2	10.5	1.5	8.9	115
^t PHZ	G and DIR	A or B	2	11	2	7.7	1.5	7.7	ns
t _{PLZ}	G and DIK	AUIB	2	11	2	7.7	1.5	7.7	115
^t PLH	CPAB or CPBA	A or B	2	10	2	7	1.5	6.3	ns
^t PHL	CPAB OF CPBA	AUID	2	10	2	7	1.5	6.3	115
^t PLH	SBA or SAB	A or B	2	12	2	8.4	1.5	7	200
^t PHL	SBA UI SAB	AUID	2	12	2	8.4	1.5	7	ns

switching characteristics over operating free-air temperature range (see Figure 2)

PARAMETER	FROM	то	CY74FC	T646T	CY74FC	Г646АТ	CY74FC1	UNIT	
PARAMETER	(INPUT) (OUTPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	B or A	1.5	9	1.5	6.3	1.5	5.4	ns
^t PHL	A 01 B	BOIA	1.5	9	1.5	6.3	1.5	5.4	115
^t PZH	DIR	A or B	1.5	14	1.5	9.8	1.5	7.8	ns
tpzL		AOIB	1.5	14	1.5	9.8	1.5	7.8	115
t _{PHZ}	G and DIR	A or B	1.5	9	1.5	6.3	1.5	6.3	ns
t _{PLZ}	G and DIK	AOIB	1.5	9	1.5	6.3	1.5	6.3	115
t _{PLH}	CPAB or CPBA	A or B	1.5	9	1.5	6.3	1.5	5.7	ns
t _{PHL}	CFAB OI CFBA	AOIB	1.5	9	1.5	6.3	1.5	5.7	115
^t PLH	SBA or SAB	A or B	1.5	11	1.5	7.7	1.5	6.2	ns
^t PHL	3BA 01 3AB	AOIB	1.5	11	1.5	7.7	1.5	6.2	115



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

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